

### 描述 / Descriptions

SOD-123 塑封封装 稳压二极管。  
Zener Diode in a SOD-123 Plastic Package.

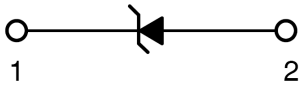
### 特征 / Features

500mW 功耗, 中等电流, 自动贴片组装。无卤产品。  
500mW power dissipation, medium current, automated assembly processes. HF Product.

### 用途 / Applications

适用于 2.4V-39V 的宽范围稳压电路。  
2.4V to 39V wide zener voltage range applications.

### 内部等效电路 / Equivalent Circuit



### 引脚排列 / Pinning



PIN1:Cathode      PIN2:Anode

### 放大及印章代码 / $h_{FE}$ Classifications & Marking

见电性能参数。 See Electrical Characteristics.

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Forward Voltage (Note 2) ( I <sub>F</sub> =10mA)	V <sub>F</sub>	0.9	V
Power Dissipation(Note 1)	P <sub>D</sub>	500	mW
Typical Thermal Resistance Junction to Ambient	R <sub>θJA</sub>	305	°C/W
Junction and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-65~150	°C

**电性能参数 / Electrical Characteristics(Ta=25°C)**

Type Number	Mark-ing Code	Zener Voltage Range (Note 2)				Maximum Zener impedance (Note 3)			Maximum Reverse Current (Note 2)		Typical Temperature Coefficient @I <sub>ZTC</sub> mV/°C		Test Current I <sub>ZTC</sub> mA
		V <sub>Z</sub> @I <sub>ZT</sub>			I <sub>ZT</sub>	Z <sub>ZT</sub> @I <sub>ZT</sub>	Z <sub>ZK</sub> @I <sub>ZK</sub>	I <sub>ZK</sub>	I <sub>R</sub>	@V <sub>R</sub>	Min	Max	
		Nom (V)	Min (V)	Max (V)	mA	Ω		mA	uA	V			
BZT52C2V4	HWX	2.4	2.2	2.6	5	100	600	1	50	1	-3.5	0	5
BZT52C2V7	HW1	2.7	2.5	2.9	5	100	600	1	20	1	-3.5	0	5
BZT52C3V0	HW2	3.0	2.8	3.2	5	95	600	1	10	1	-3.5	0	5
BZT52C3V3	HW3	3.3	3.1	3.5	5	95	600	1	5	1	-3.5	0	5
BZT52C3V6	HW4	3.6	3.4	3.8	5	90	600	1	5	1	-3.5	0	5
BZT52C3V9	HW5	3.9	3.7	4.1	5	90	600	1	3	1	-3.5	0	5
BZT52C4V3	HW6	4.3	4	4.6	5	90	600	1	3	1	-3.5	0	5
BZT52C4V7	HW7	4.7	4.4	5	5	80	500	1	3	2	-3.5	0.2	5
BZT52C5V1	HW8	5.1	4.8	5.4	5	60	480	1	2	2	-2.7	1.2	5
BZT52C5V6	HW9	5.6	5.2	6	5	40	400	1	1	2	-2	2.5	5
BZT52C6V2	HWA	6.2	5.8	6.6	5	10	150	1	3	4	0.4	3.7	5
BZT52C6V8	HWB	6.8	6.4	7.2	5	15	80	1	2	4	1.2	4.5	5
BZT52C7V5	HWC	7.5	7	7.9	5	15	80	1	1	5	2.5	5.3	5
BZT52C8V2	HWD	8.2	7.7	8.7	5	15	80	1	0.7	5	3.2	6.2	5
BZT52C9V1	HWE	9.1	8.5	9.6	5	15	100	1	0.5	6	3.8	7	5
BZT52C10	HWF	10	9.4	10.6	5	20	150	1	0.2	7	4.5	8	5

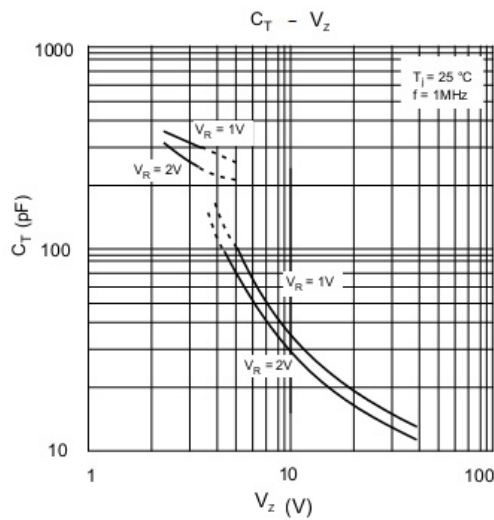
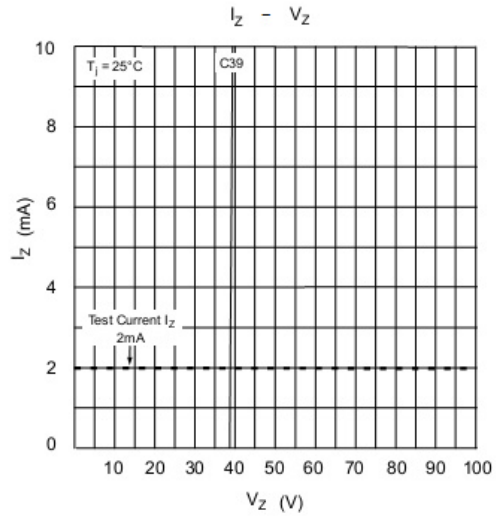
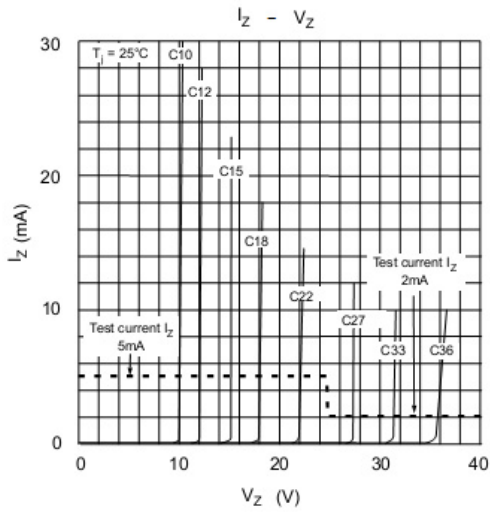
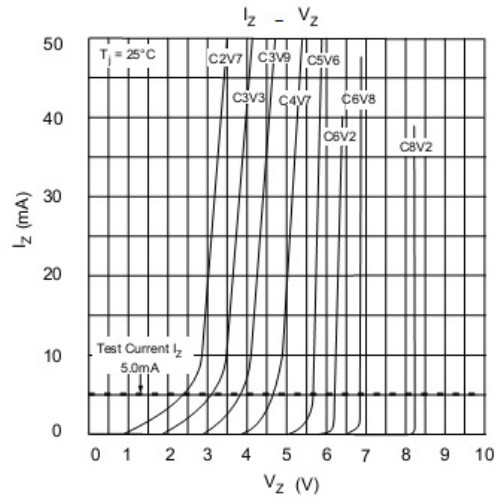
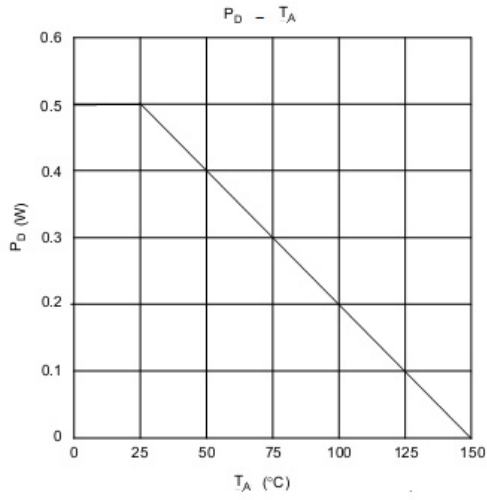
**电性能参数 / Electrical Characteristics(Ta=25°C)**

Type Number	Marking Code	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 3)			Maximum Reverse Current (Note 2)		Typical Temperature Coefficient @I <sub>ZTC</sub> mV/°C		Test Current I <sub>ZTC</sub> mA
		V <sub>Z</sub> @I <sub>ZT</sub>			I <sub>ZT</sub>	Z <sub>ZT</sub> @I <sub>ZT</sub>	Z <sub>ZK</sub> @I <sub>ZK</sub>	I <sub>ZK</sub>	I <sub>R</sub>	@V <sub>R</sub>	Min	Max	
		Nom (V)	Min (V)	Max (V)	mA	Ω		mA	uA	V			
BZT52C11	HWG	11	10.4	11.6	5	20	150	1	0.1	8	5.4	9	5
BZT52C12	HWH	12	11.4	12.7	5	25	150	1	0.1	8	6	10	5
BZT52C13	HWI	13	12.4	14.1	5	30	170	1	0.1	8	7	11	5
BZT52C15	HWJ	15	13.8	15.6	5	30	200	1	0.1	10.5	9.2	13	5
BZT52C16	HWK	16	15.3	17.1	5	40	200	1	0.1	11.2	10.4	14	5
BZT52C18	HWL	18	16.8	19.1	5	45	225	1	0.1	12.6	12.4	16	5
BZT52C20	HWM	20	18.8	21.2	5	55	225	1	0.1	14	14.4	18	5
BZT52C22	HWN	22	20.8	23.3	5	55	250	1	0.1	15.4	16.4	20	5
BZT52C24	HWO	24	22.8	25.6	5	70	250	1	0.1	16.8	18.4	22	5
BZT52C27	HWP	27	25.1	28.9	2	80	300	0.5	0.1	18.9	21.4	25.3	2
BZT52C30	HWQ	30	28	32	2	80	300	0.5	0.1	21	24.4	29.4	2
BZT52C33	HWR	33	31	35	2	80	325	0.5	0.1	23.1	27.4	33.4	2
BZT52C36	HWS	36	34	38	2	90	350	0.5	0.1	25.2	30.4	37.4	2
BZT52C39	HWT	39	37	41	2	130	350	0.5	0.1	27.3	33.4	41.2	2

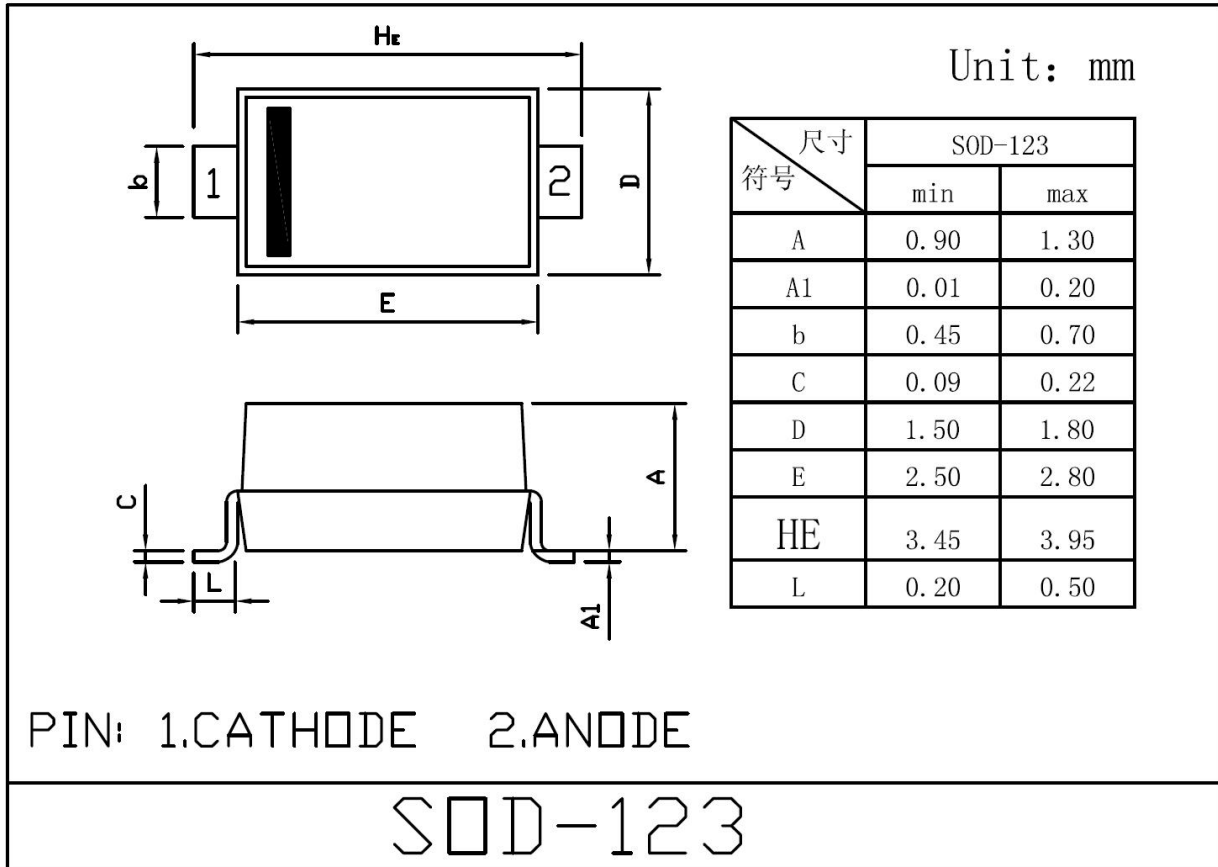
Notes:

1. Device mounted on ceramic PCB; 7.6mm x 9.4mm x 0.87mm with pad areas 25mm<sup>2</sup>.
2. Short duration test pulse used to minimize self-heating effect.
3. f = 1kHz.

**电参数曲线图 / Electrical Characteristic Curve**



外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions



说明：

H： 为公司代码

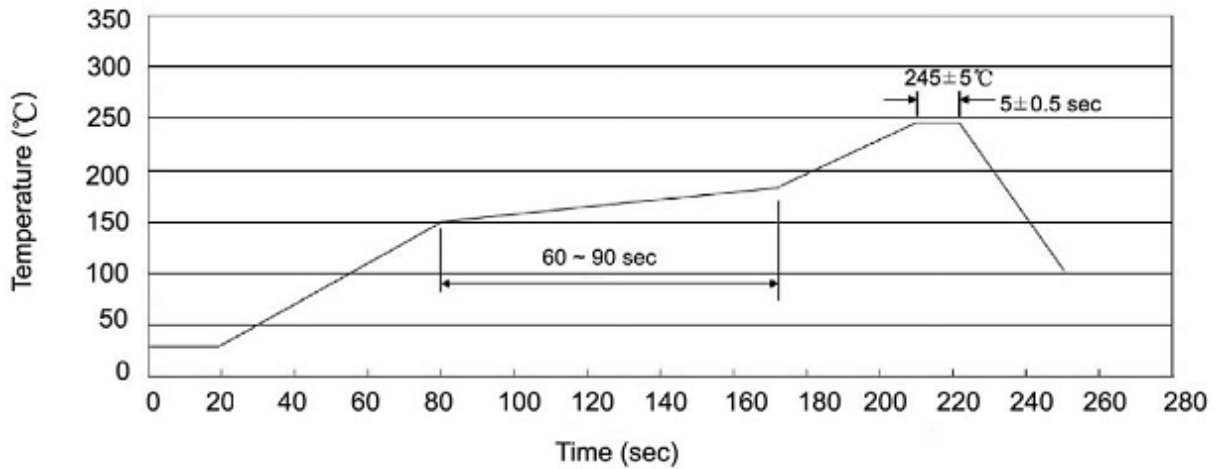
WX： 为型号代码

Note:

H: Company Code.

WX: Product Type.

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-123	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

**使用说明 / Notices**